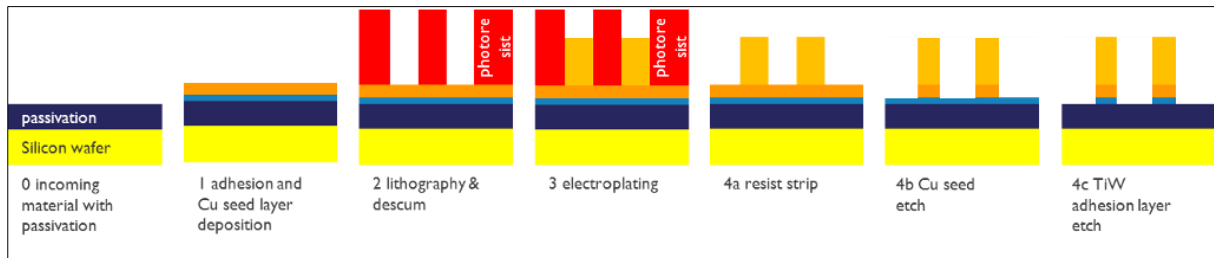


10th ASCENT Newsletter – July 2018

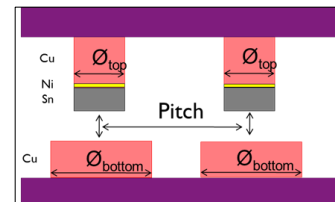
#1

New offer: imec 3D packaging



imec has extended its ASCENT offer to include semi-additive uBumping or Cu pillar processing for researchers with previously processed Si CMOS or MEMS wafers.

Additionally they can offer short loop uBump or Cu pillar wafer preparation for specific characterization activities (e.g. metrology development, Failure Analysis understanding etc). Larger integration projects may be considered on a case by case basis.



Please don't hesitate to send me any questions relating to this new

offer or indeed any queries about the ASCENT programme – paul.roseingrave@tyndall.ie



This project has received funding from the *European Union's Horizon 2020 research and innovation programme* under grant agreement No 654384.

#2

See you @ IEEE Nano 2018 – Cork, Ireland



The IEEE International Conference on Nanotechnology hosts the 18th Conference in Cork, Ireland from 24th to 26th July 2018 and ASCENT will also be there. This is an ideal opportunity to meet with and discuss the ASCENT offer.

Visit Tyndall: We can also arrange for you to visit Tyndall to get a better understanding of the research facilities available through this EU funded programme.

This conference attracts both academic and industry based researchers which also offers tutorials / meetings on Monday 23rd July.

The conference scope spans nanoscience and nanotechnology, from fundamentals in nanomaterials, nanofabrication and nano-characterisation to development of nanosensors, nanoactuators and nanoelectronic or nanophotonic devices.

A special invited industry session will take place on Thursday 24th July entitled *Opportunities and Challenges for Nano-Enabled Smart Things*

More information and registration: <http://ieeenano18.org/>

To arrange a meeting with an ASCENT representative or a visit to Tyndall please contact:

Paul (ASCENT Access Co-ordinator): paul.roseingrave@tyndall.ie



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#3

Time running out - Limited access days remain



The ASCENT infrastructure access programme is now running three and a half years providing either direct, remote or virtual access to the world's most advanced CMOS technologies and infrastructure.

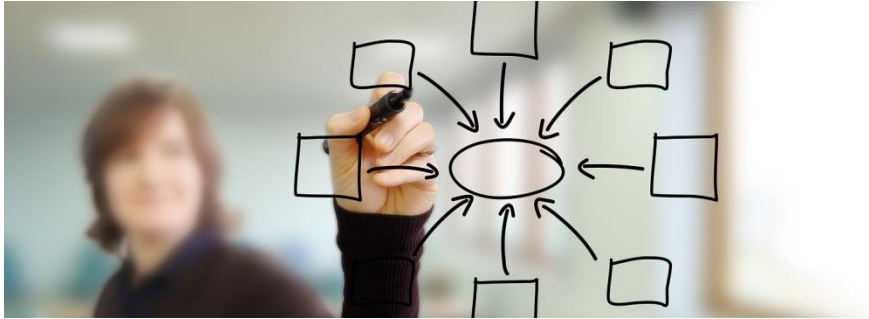
The programme is closing in 10 months' time and only limited access days remain so we are reminding all nanoelectronic researchers to apply now ... before it is too late.

This programme has been designed for easy access, including rapid response to enquiries, short proposal templates and swift review turnaround times. Also the access provided to three top Nanoelectronics Researcher Institutes across Europe – imec, CEA Leti & Tyndall National Institute – is free of charge to you – once you commit to publishing your results.

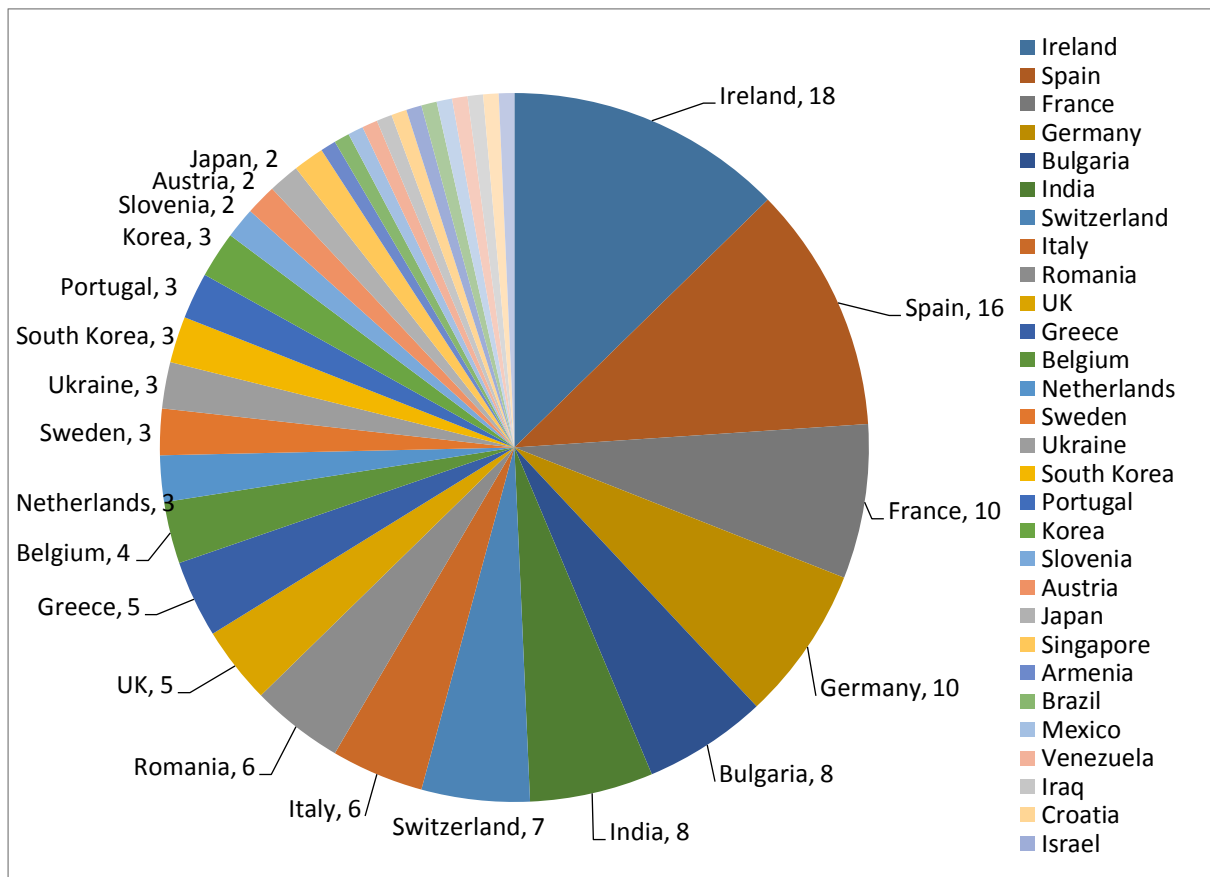
For any enquiries, email Paul (ASCENT Access Co-ordinator): paul.roseingrave@tyndall.ie

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#4 ASCENT Statistics



ASCENT launched in November 2015 and since then has attracted a network of over 350 members, who have submitted 142 enquiries resulting in 73 Virtual and Transnational researchers accessing ASCENT facilities ...



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#5

ESSDERC/ESSCIRC 2018 & ASCENT Workshop – Dresden, Germany



This Conference will take place in Dresden, Germany from Monday 3rd to Thursday 6th September 2018.

ASCENT will once again attend and be available for meeting/discussions to all attendees to outline how this Infrastructure Access project works and what benefits it can offer to researchers, from both academia and industry.

Conference information: <https://www.esscirc-essderc2018.org/>

MOS-AK / ASCENT Workshop



ASCENT will, in conjunction with MOS-AK, host a Workshop on Monday 3rd September. The specific workshop goal will be to classify the most important directions for the future development of the electron device models, not limiting the discussion to compact models, but including physical, analytical and numerical models, to clearly identify areas that need further research and possible contact points between the different modelling domains.

Workshop information: http://www.mos-ak.org/dresden_2018/

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